



HIGHER EDUCATION LOANS BOARD

INVITATION TO TENDER

Date: 16th November 2021

TENDER REF: HELB/T/05 /2021 - 2022

PROVISION OF Security Information and Event Management (SIEM) Solution, Configuration, Licensing, Warranty & Partnership

The Higher Education Loans Board is a state corporation whose mandate is to source for funds and provide loans, scholarships and bursaries to Kenyans studying in recognized institutions of higher learning.

HELB invites sealed tenders from interested, eligible and qualified firms that are **manufacturer authorized or authorized warranty centers** for the **Provision of Security Information and Event Management (SIEM) Solution, Licensing, Warranty & Partnership**. Interested and eligible firms may view the detailed tender advert, respective tender document and further details regarding the tender submission from our website www.helb.co.ke/procurement/ or Public Procurement Information Portal <https://tenders.go.ke>. Tender documents downloaded from the two websites are free of charge. All bidders interested in participating in the tender are required to forward their contact details on email to procurement@helb.co.ke in case of any further tender addendum.

Interested bidders shall be required to submit **one (1) original** and **one soft copy** of their **combined technical** and **financial** proposals, which shall be clearly marked “**ORIGINAL**” and “**SOFT COPY**” as appropriate. In the event of any discrepancy between them, the original shall govern. All Bidders **must serially number all the pages including the inserts in their tender proposal submission from the 1st page to the last page** in the format 1,2,3,4,5....as the number of pages received in each bidder’s tender submission proposal will be recorded during the tender opening.

The completed tender submission documents, wrapped in one envelope clearly marked: HELB/T/05/2020-2021: ‘PROVISION OF Security Information and Event Management (SIEM) Solution, configuration, Licensing, Warranty & Partnership’ should be deposited in the tender box located at Anniversary Towers 18th floor lift lobby, University Way or sent by post to:

**The Chief Executive Officer
Higher Education Loans Board
P. O. Box 69489 – 00400
NAIROBI**

so as to be received not later than **Wednesday 24th November 2021 2021** at **11.00 a.m.** Opening of the submitted tenders will take place immediately on the same date in the main boardroom on 19th floor, Anniversary Towers at **11.15 a.m.**

Interested bidders are invited to witness the opening, **however due to COVID-19** a restricted number will be allowed as per the Ministry of Health and WHO guidelines to be held at the main boardroom on 19th floor on the same day at 11.15 a.m.

Prices quoted should be net inclusive of all taxes and delivery costs, must be expressed in Kenya shillings and shall remain valid for period of (120) days from the closing date of the tender.

All tenders **must** be accompanied by a tender security of **Kshs.350,000.00** in the **form of a bank guarantee** from a reputable bank, **a bankers cheque, insurance from companies authorized to transact in bid bonds, letter of credit or a guarantee by a deposit taking microfinance institution, Sacco Society, Youth Enterprise Fund or Women Enterprise Fund** and valid for a period of **120 days** from the day of opening the tender. AGPO registered firms are not required to submit a tender security but **must fill, sign and submit the Tender Securing Declaration form** and **must submit the valid AGPO registration certificate**. Please note that any tender that shall not be accompanied by a **tender security** or a filled and signed Tender Securing Declaration form and Valid **AGPO certificate** shall be deemed to be non-responsive and disqualified.

HELB may at any time terminate the procurement proceedings without entering into a contract in accordance with section 63 of the Public Procurement and Asset Disposal Act 2015.

**CHIEF EXECUTIVE OFFICER
HIGHER EDUCATION LOANS BOARD**